

ABSTRACT

There is provided a flux for soldering and a soldering process which form better solder connection without the occurrence of the poor connection nor the insulation degradation.

Such flux which is placed between a solder portion formed on a first electrode and a second electrode when the first electrode is soldered to the second electrode contains:

a liquid base material made of a resin component which is dissolved in a solvent,

an active component which removes an oxide film, and

a metal powder made of a metal of which melting point is higher than that of a solder material which forms the solder portion, and

the flux contains the metal powder in an amount in the range between 1 % and 9 % by volume based on a volume of the flux.